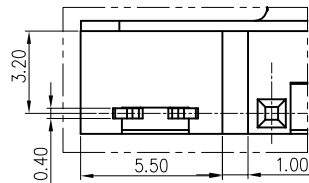
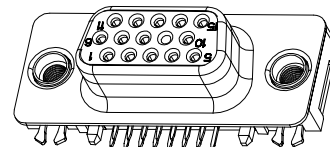


REVISION RECORD		
REV	DESCRIPTION	DRFT



DETAIL B
SCALE: 2:1



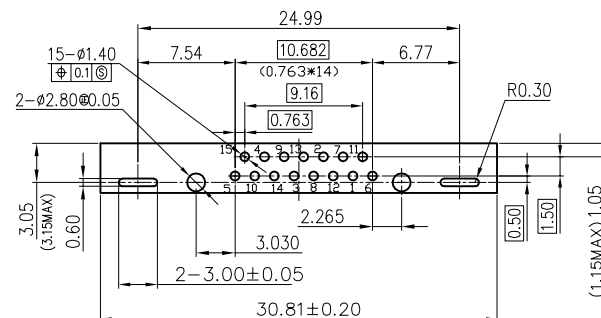
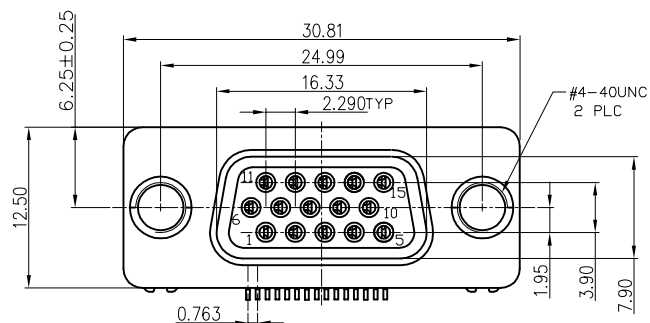
NOTES:

1. MATERIAL:
 1.1 HOUSING & COVER: LCP WITH 30% G.F, UL94 V-0 COLOR: BLACK
 1.2 CONTACT: COPPER ALLOY;
 1.3 METAL POST: COPPER ALLOY;
 1.4 SHIELD: COPPER ALLOY;
 1.5 RIVET: COPPER ALLOY;

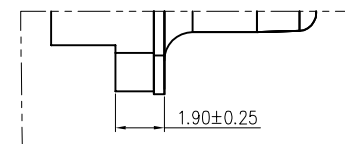
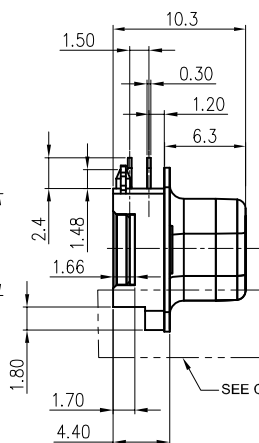
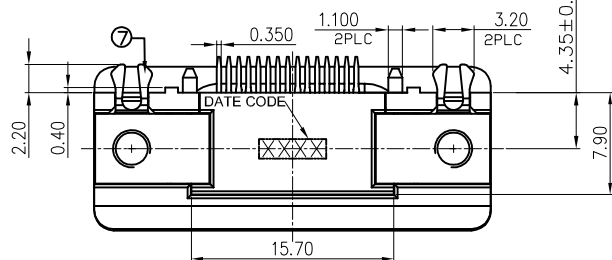
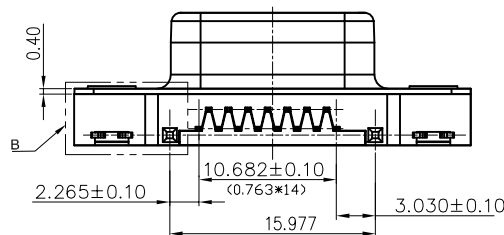
2. FINISH:

- 2.1 CONTACT:
 GOLD PLATED 1u" ON CONTACT AREA.
 2.54um [100u"] MIN. TIN PLATED ON SOLDER TAIL AREA.
 1.27um [50u"] MIN. NICKEL UNDERPLATED OVERALL.
 2.2 METAL POST:
 2.54um [100u"] MIN. TIN PLATED
 1.27um [50u"] MIN. NICKEL UNDERPLATED OVERALL.
 2.3 SHIELD:
 1.27um [50u"] MIN. NICKEL UNDERPLATED OVERALL.
 2.4 RIVET:
 1.27um [50u"] MIN. NICKEL UNDERPLATED OVERALL.

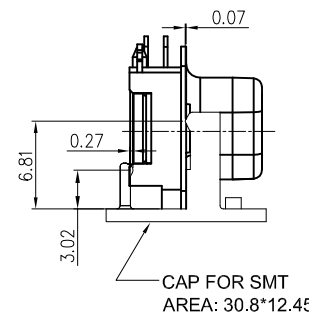
3. RECOMMENDED P.C.B THICKNESS : 1.6mm
 4. OTHER GENERAL SPEC. TO REFER : D-SUB SERIES SPEC.
 5. FOR WAVE SOLDERING LEAD-FREE PROCESS



PCB LAYOUT



DETAIL C
SCALE: 2:1



MM (INCH)		DFTD Roy	DATE 12/17/2012	Pulse Electronics		RoHS Compliant	
TOLERANCES EXCEPT AS NOTED		CHKD	DATE	TITLE			
.0 ± .035		APPVL	DATE	SLIM D-SUB15P FEMALE (SINKING BOARD)			
.00 ± .025		MATERIAL :		DRAWING NO. E9215-001-01		SIZE	REV
.000 ± .015		FINISH :		/PART NO. E9215-001-01		A3	01
ANGLES :		SCALE : 1:1		DO NOT SCALE DRAWING		SHEET	1 OF 1
THIRD ANGLE PROJECTION							